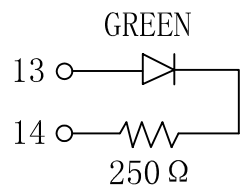
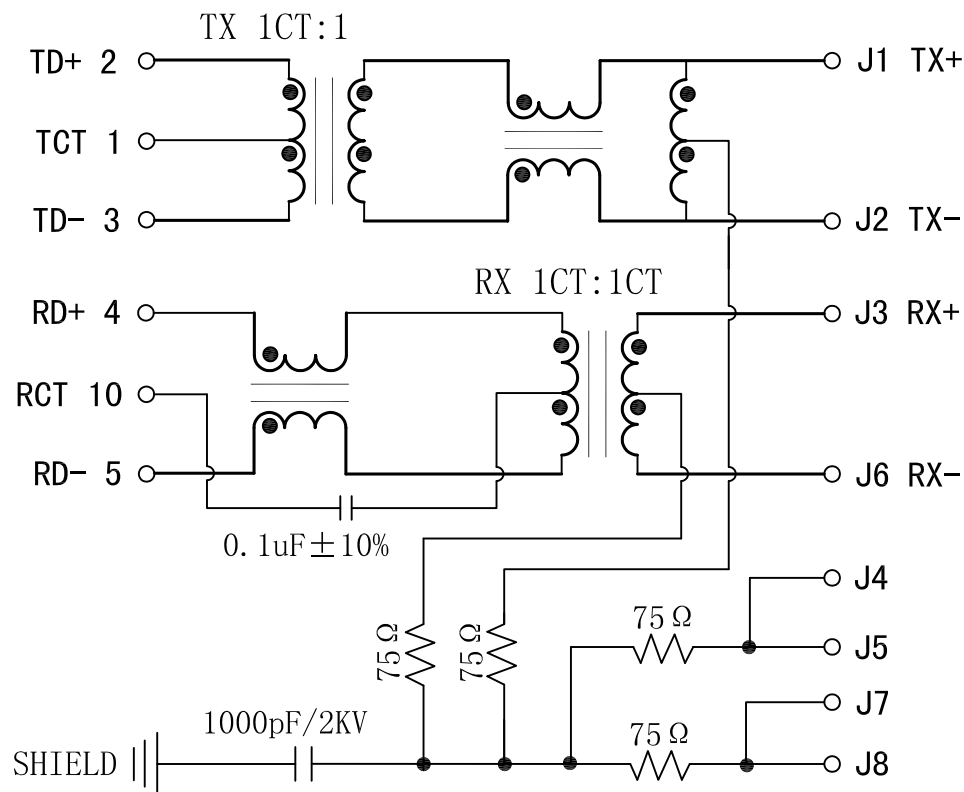
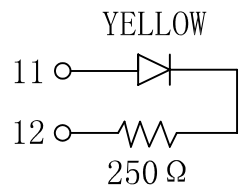


Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2010/11/03	



LEFT LED



RIGHT LED



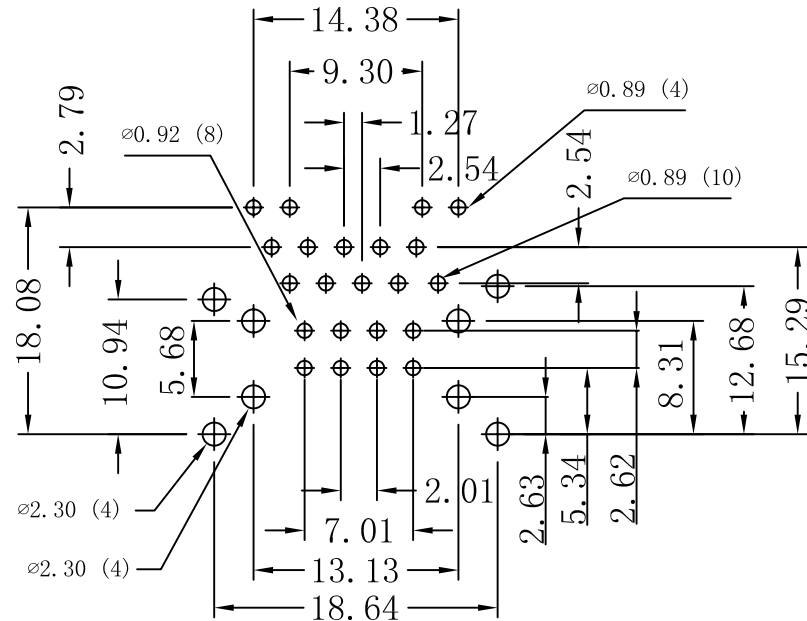
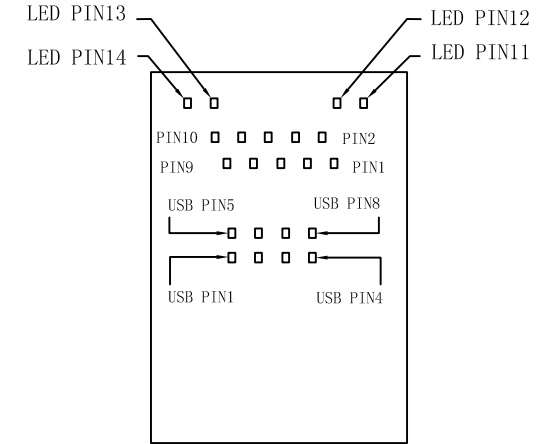
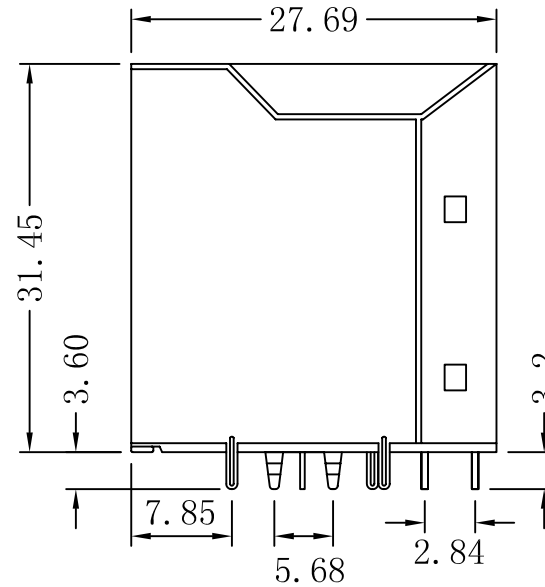
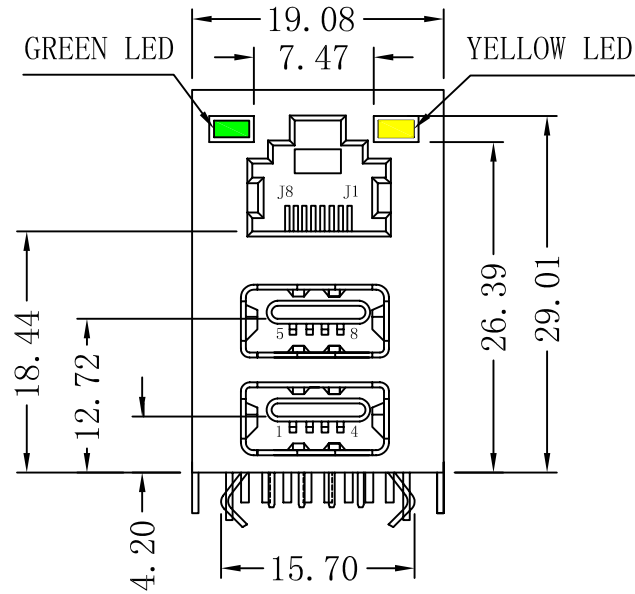
Electrical Specifications @25°C

- Turns Ratio:
TX=1CT:1 ±3%
RX=1CT:1CT ±3%
- OCL: (100KHz, 100mVRMS, 8mA, DC BIAS)
350uH MIN
- Hipot (Isolation Voltage): 1500Vrms
- Insertion Loss:
-1.0dB MAX @ 100KHz TO 100MHz
- Return Loss:
-20dB MIN @ 1MHz TO 30MHz
-[19-20LOG(F/30MHz)]dB MIN @30MHz TO 60MHz
-12dB MIN @ 60MHz TO 80MHz
- Cross Talk:
-35dB MIN @ 1MHz TO 65MHz
-30dB MIN @ 65MHz TO 100MHz
- Common To Common Mode Rejection:
-30dB MIN @ 100KHz TO 100MHz
-20dB MIN @ 100MHz TO 130MHz
- Operating Temperature: 0~70°C

X:X ±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED
X:XX ±0.20	CHKD:	
X:XXX ±0.10	DR: TOM	Title: RJ45 10/100BASE-TX JACK/ Dual USB Combo
ANGLES ±1°	UNIT: mm	PART NO.: LPJU5009B28NL
	SCALE: 2/1	SHEET: 1/2
	REV: A	DWG NO.: LP10110310

Mechanical :

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2010/11/03	



SUGGESTED PCB LAYOUT (TOP VIEW)



NOTES:

1. Designed to support application, such as SOHO (ADSL modems), LAN-on-Motherboard (LOM), hub and Switches.
2. Meets IEEE 802.3 specification
3. Connector Materials:
 Housing: Thermoplastic UL94V-0
 Contact/Shield: Copper alloy
 Shield plating: Nickel
 Contact plating: Gold 6 micro-inches min. In contact area.
 USB Contact plating: Gold flash.
4. Wave solder tip temperature: 265°C Max
 Wave solder tip temperature time: 5 Sec Max

X:X	±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED
X:XX	±0.20	CHKD:	
X:XXX	±0.10	DR: TOM	Title: RJ45 10/100BASE-TX JACK/ Dual USB Combo
ANGLES	±1°	UNIT: mm	PART NO.: LPJU5009B28NL
	SCALE: 2/1	SHEET: 2/2	REV: A DWG NO.: LP10110310